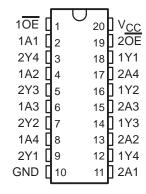
- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low-Static Power Dissipation
- Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Supports Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce)
 < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Supports Live Insertion
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW)
 Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Packages, and Ceramic (J) DIPs

description

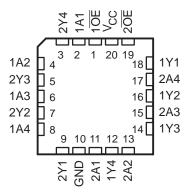
These octal buffers and line drivers are designed specifically for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

The 'LVTT240 is organized as two 4-bit buffer/line drivers with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the device passes data from the A inputs to the Y outputs. When \overline{OE} is high, the outputs are in the high-impedance state.

SN54LVTT240 ... J OR W PACKAGE SN74LVTT240 ... DB, DW, OR PW PACKAGE (TOP VIEW)



SN54LVTT240 ... FK PACKAGE (TOP VIEW)



To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

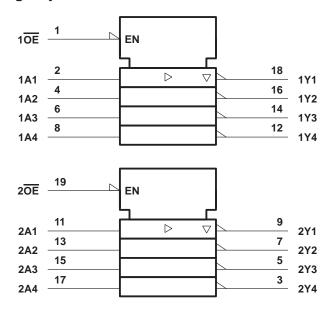
The SN74LVTT240 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54LVTT240 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74LVTT240 is characterized for operation from -40° C to 85° C.

FUNCTION TABLE (each buffer)

ĺ	INPU	JTS	OUTPUT
	OE	Α	Υ
	L	Н	L
ı	L	L	Н
ı	Н	Χ	Z

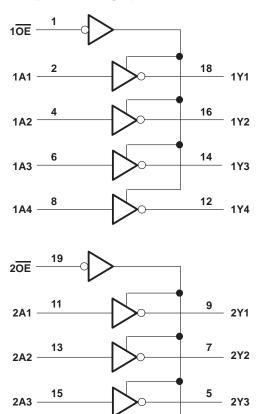
logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)

2A4 -



- 2Y4

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}	-0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)	
Voltage range applied to any output in the high state or power-off state, V _O (see Note 1)	. -0.5 V to 7 V
Current into any output in the low state, IO: SN54LVTT240	96 mA
SN74LVTT240	128 mA
Current into any output in the high state, I _O (see Note 2): SN54LVTT240	48 mA
SN74LVTT240	64 mA
Input clamp current, I _{IK} (V _I < 0)	−50 mA
Output clamp current, I_{OK} ($V_O < 0$)	−50 mA
Maximum power dissipation at T _A = 55°C (in still air) (see Note 3): DB package	0.6 W
DW package	1.6 W
PW package	0.7 W
Storage temperature range	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. This current flows only when the output is in the high state and $V_O > V_{CC}$.

3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 4)

						SN74LVTT240		
		MIN	MAX	MIN	MAX	UNIT		
Vсс	Supply voltage	2.7	3.6	2.7	3.6	V		
VIH	High-level input voltage	2	EN	2		V		
V _{IL}	Low-level input voltage		0.8		0.8	V		
VI	V _I Input voltage					5.5	V	
IOH	IOH High-level output current					-32	mA	
l _{OL}	Low-level output current	200	48		64	mA		
Δt/Δν	Input transition rise or fall rate	Outputs enabled	20	10		10	ns/V	
TA	Operating free-air temperature	-55	125	-40	85	°C		

NOTE 4: Unused or floating control inputs must be held high or low.



SN54LVTT240, SN74LVTT240 3.3-V ABT OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS				54LVTT2	240	SN74LVTT240			LINUT
PARAMETER					MIN TYPT MAX		MIN TYPT MAX		UNIT	
VIK	$V_{CC} = 2.7 \text{ V},$	I _I = -18 mA			-1.2			-1.2	V	
	$V_{CC} = MIN \text{ to } MAX^{\ddagger},$	V _{CC} -C).2		VCC-0).2				
V	V _{CC} = 2.7 V,	I _{OH} = – 8 mA	2.4			2.4			V	
VOH	Vac - 2 V	I _{OH} = – 24 mA	2							
	VCC = 3 V	$I_{OH} = -32 \text{ mA}$				2				
	V _{CC} = 2.7 V	I _{OL} = 100 μA			0.2			0.2		
	VCC = 2.7 V	I _{OL} = 24 mA			0.5			0.5		
\/a.		I _{OL} = 16 mA				0.4			0.4	V
VOL	V _{CC} = 3 V	I _{OL} = 32 mA				0.5			0.5	
		I _{OL} = 48 mA			0.55					
		I _{OL} = 64 mA				0.55				
1.	$V_{CC} = 0$ or MAX‡,		751	10			10	μΑ		
11	V _{CC} = 3.6 V	$V_I = V_{CC}$ or GND			,Q	±1			±1	μΑ
l _{off}	$V_{CC} = 0$,	V_I or $V_O = 0$ to 4.5 V			, , ,				±100	μΑ
I _{OZH}	$V_{CC} = 3.6 \text{ V},$	V _O = 3 V		\delta C	Ž,	5			5	μΑ
lozL	$V_{CC} = 3.6 \text{ V},$	$V_0 = 0.5 V$		00		-5			-5	μΑ
	V _{CC} = 3.6 V,	I _O = 0,	Outputs high		0.12	0.19		0.12	0.19	
lcc			Outputs low		8.6	12		8.6	12	m _A
.00	V _I = V _{CC} or GND		Outputs disabled		0.12	0.19		0.12	0.19	1117 (
ΔlCC§	V_{CC} = 3 V to 3.6 V, One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or GND					0.2			0.2	mA
Ci	V _I = 3 V or 0				4			4		pF
Со	$V_O = 3 \text{ V or } 0$				8			8		pF

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

		TO (OUTPUT)	SN54LVTT240				SN74LVTT240									
PARAMETER	FROM (INPUT)		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V			V _{CC} = 2.7 V		UNIT				
			MIN	MAX	MIN	MAX	MIN	TYP	MAX	MIN	MAX					
tPLH	Α		1	4.2	N	5.2	1	2.9	4.1		5.2	ns				
^t PHL		T	1.3	3.7	PA	4.1	1.3	2.5	3.5		4	113				
^t PZH	ŌĒ	ŌĒ		1.2	4.7/	,	5.7	1.2	3.2	4.6		5.6	ns			
t _{PZL}			ı	1.5	4.8		5.9	1.4	3.5	4.7		5.8	115			
^t PHZ	ŌĒ	ŌĒ	V	2	5.3		5.7	2	3.6	5.2		5.5	ns			
tPLZ			OL	' [1	1	ľ	ľ	1.9	4.6		4.6	1.9	3.2	4.4	

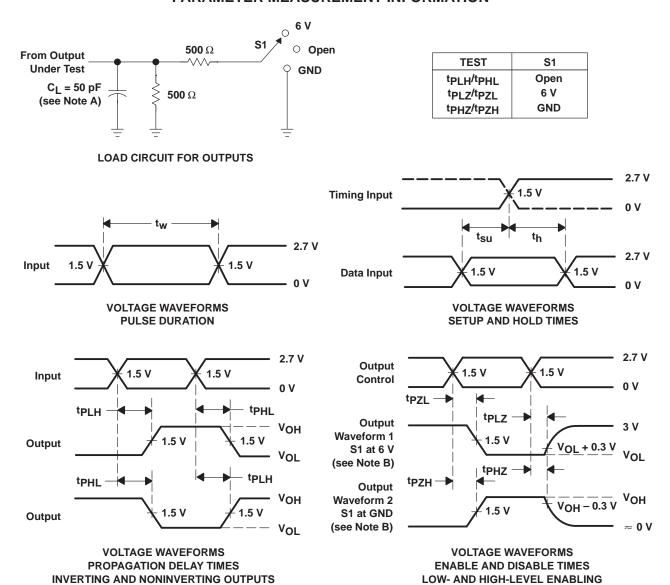
[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.



For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq 2.5$ ns, $t_f \leq 2.5$ ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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